

SolderStar PRO - Reflow Profiling Solutions

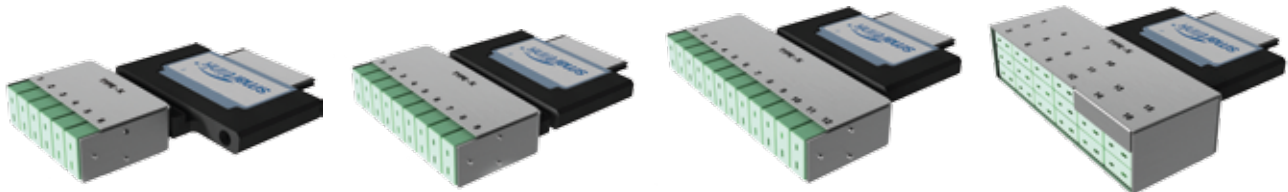
Featuring SolderStar
smartlink[★]
connection System



Smartlink Thermal Barrier Concept
(9 Channel Version Pictured)



Miniature Profiling Datalogger



Thermocouple Adapters available in 6,9,12 or 16 Channel versions

Reflow Profiling upto 16 Measurement Channels

The package includes an ultra compact datalogger featuring the unique 'SmartLink' connector system, combined with a heatshield and thermocouple adapter to provide the number of measurement channels required.

Future upgrading or servicing is a simple and cost effective procedure, with only the Thermocouple Adapter needing to be changed to allow 6,9,12 or 16 Type-K measurement versions.

The 'SmartLink' concept allows high measurement channel configurations, while maintaining a small footprint and quick connection to a range of accessories for capture of profile and SPC information from reflow, wave/selective and vapour phase soldering processes.

A comprehensive suite of software includes profile analysis, data management, profile simulations and integrated SPC charting tools. This easy to use system is ideal for manufacturers and EMS providers who require rapid profile setup followed by periodic measurements to control their solder process quality.

System Advantages

- Compact size for profiling of narrow PCB formats or ovens with low tunnel clearance
- Support for 6 to 16 measurement channels for profiling of the most complex PCB assemblies
- Unique SmartLink connection system provides quick datalogger connection to a range of products and accessories
- Software tools including profile analysis and simulation, plus integrated SPC management features
- Connectivity via standard USB cables or 2.4Ghz Wireless Telemetry
- Extendable for control of wave / selective or vapour phase soldering

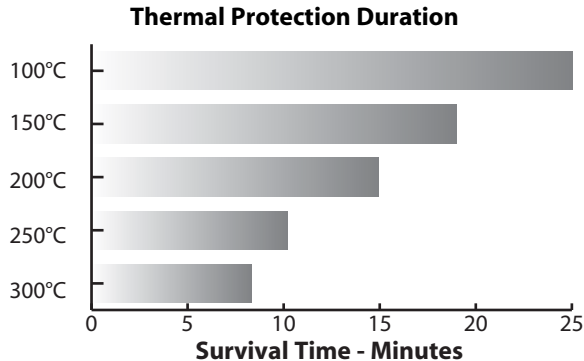
Datalogger

Technical Data

| | |
|---------------------------|---|
| Size/Weight | 125mm x 52mm x 9mm, 110g |
| Channels | 6,9,12 or 16 Channel Versions Available |
| Memory | 120,000 Memory Points |
| Sampling | 0.1s to 10 Minutes |
| Measurement Range | -150 to 600 °C |
| Accuracy | ±0.5 °C |
| Resolution | ±0.02 °C |
| Max. Internal Temperature | +85 °C (Auto Shutdown on over temp.) |
| Power | Rechargeable High Temperature Nimh |
| Communications | USB (Type A - Mini B) or 2.4Ghz Wireless |
| Thermocouples | Type K, EN 05842:1993 Class 1 / ANSI MC 96.1 |

Heatshield

| | |
|--------------|--|
| Material | Stainless Steel |
| Size (LxWxH) | 6/9 Channel Version: 310mm x 80mm x 25mm 12 Channel Version: 310mm x 104mm x 25mm 16 Channel Version: 330mm x 146mm x 25mm |



Other heatshield sizes are available for special process requirements.

Wireless Telemetry Option

| | |
|-----------|----------------------------------|
| Frequency | 2.4GHZ Transceiver |
| Channels | 128 Individual Channels |
| Protocol | Zigbee PRO - Duplex Transmission |



Software

| | |
|------------------|--|
| Compatibility | Windows™ XP Vista/Windows 7/8 32 & 64 Bit |
| Language Support | English, French, German, Italian, Portuguese, Spanish & Chinese |

Standard Equipment

- SolderStar PRO datalogger
- Thermocouple Adapter
- 25mm Lead Free capable heatshield
- Type K thermocouples
- PC Analysis software
- Hard copy manual + 1 Year calibration certificate
- Equipment case

Optional Reflow Equipment

- AUTOSeeker Profiler Optimisation software
- 2.4Ghz Wireless Telemetry
- Deltaprobe Oven Verification fixture
- Adjustable Reflow Carrier

Additional Process Support



REFLOW • WAVE • VAPOUR

A range of process specific accessories are available to extend the system for use with Reflow, Wave/Selective Soldering and Vapour Phase processes.

SolderStar Ltd
Manchester UK
Tel: +44 (0)1706 354846
Fax: +44 (0)1706 675296
Email: info@solderstar.com
www.solderstar.com